


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 30 December 2013 [Approved: 15 January 2025 11:11 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	3.27%	Silicon	7440-21-3	100%
			Carbon black	1333-86-4	0.5%
			Quartz Exempt from other regulatory requirements	14808-60-7	2.5%
Encapsulation	EP (Epoxy resin)	57.48%	Magnesium hydroxide	1309-42-8	10%
			phenolic epoxy resin	61788-97-4	10%
			Epoxy resin 89	26335-32-0	15%
			Quartz sand	60676-86-0	62%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.41%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	1.22%	Tin	7440-31-5	100%
			Copper	7440-50-8	0.168%
Leadframe	Nickel and Nickel alloys	37.62%	Silver	7440-22-4	1.196%
			Iron nickel zinc oxide REACH Article 67 Exemption	12645-50-0	98.636%

Attached parts list

Part number	Part name
SOD-523 (H) Pb&H-Free (Cu)	Diode SMD